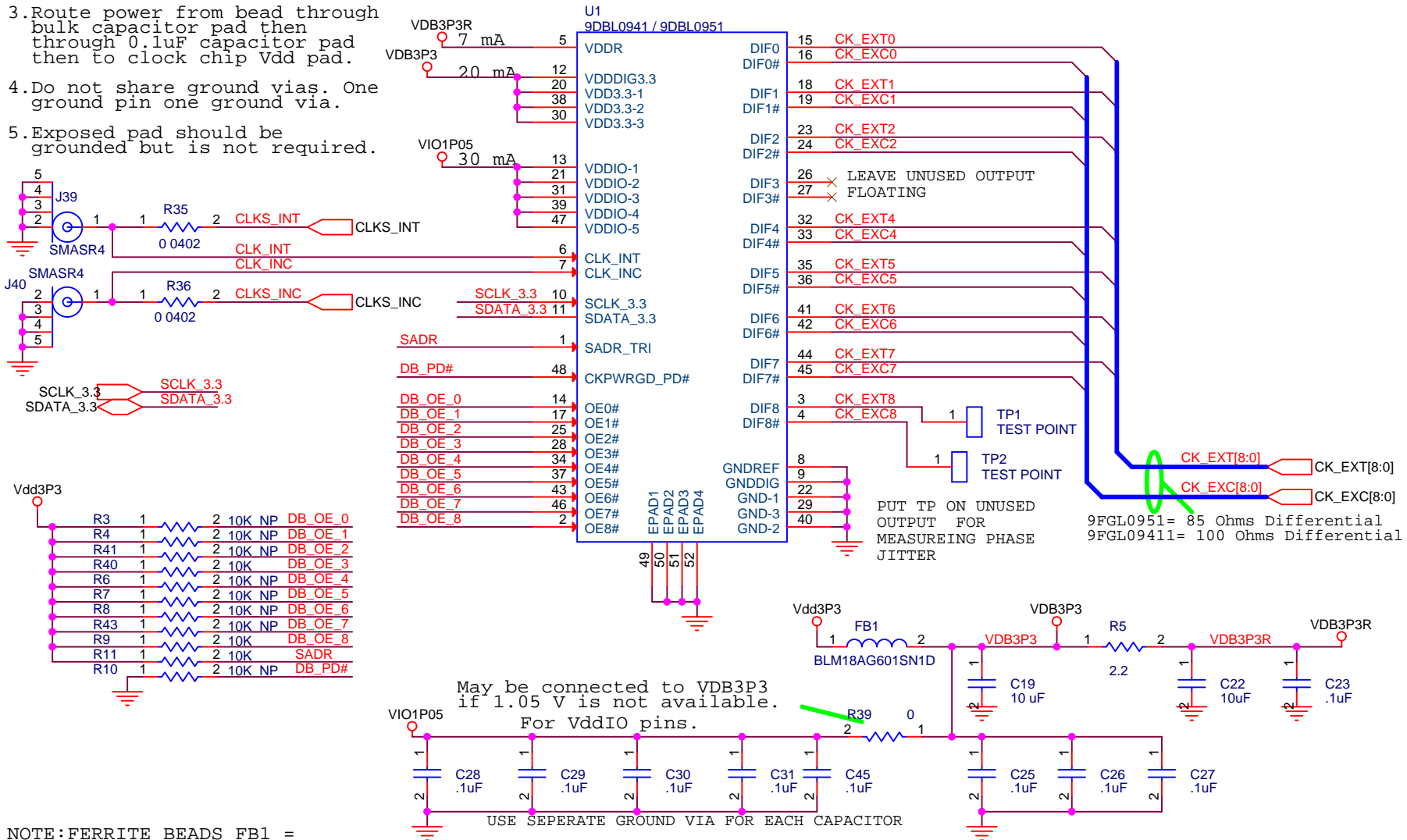


Layout notes.

- Route power from bead through bulk capacitor pad then through 0.1uF capacitor pad then to clock chip Vdd pad.
- Do not share ground vias. One ground pin one ground via.
- Exposed pad should be grounded but is not required.



NOTE:FERRITE BEADS FB1 =

Manufacture	Part Number	Z@100MHz	PkgSz	DC res.	Current(Ma)
muRata	BLM21A6G01SN1	600	0805	0.30	600
TDK	MMZ2012S601A	600	0805	0.30	600
STEWART	HZ0805E601R	600	0805	0.30	600
AssocCmpTch	CBG0805-600-50	600	0805	0.30	600

Manufacture	Part Number	Z@100MHz	PkgSz	DC res.	Current(Ma)
muRata	BLM18AG601SN1	600	0603	0.50	200
muRata	BLM18BD601SN1_PB	600	0603	0.65	200
Ceratech	HB-1T1608-601	600	0603	0.50	200
TDK	MMZ1608R301A	300	0603	0.20	500

Integrated Device Technology
San Jose, CA

Size A	Document Number 9DBL0941/9DBL0851	Rev 0.2
Date:	Thursday, September 07, 2017	Sheet 1 of 3